


**PRODUCT / PROCESS CHANGE NOTIFICATION**

**1. PCN basic data**

<b>1.1 Company</b>		STMicroelectronics International N.V
<b>1.2 PCN No.</b>	MMS/14/9012	
<b>1.3 Title of PCN</b>	STR9 products in LFBGA 10x10 package - Transfer of assembly site from STATS ChipPAC Korea 1 to STATS ChipPAC Korea 3	
<b>1.4 Product Category</b>	STR9 products in LFBGA 10x10 package	
<b>1.5 Issue date</b>	2014-12-18	

**2. PCN Team**

<b>2.1 Contact supplier</b>	
<b>2.1.1 Name</b>	ROBERTSON HEATHER
<b>2.1.2 Phone</b>	+1 8475853058
<b>2.1.3 Email</b>	heather.robertson@st.com
<b>2.2 Change responsibility</b>	
<b>2.2.1 Product Manager</b>	Michel BUFFA
<b>2.1.2 Marketing Manager</b>	Daniel COLONNA, Veronique BARLATIER
<b>2.1.3 Quality Manager</b>	Pascal NARCHE

**3. Change**

<b>3.1 Category</b>	<b>3.2 Type of change</b>	<b>3.3 Manufacturing Location</b>
Transfer of a full process or process brick (process step, control plan, recipes) from one site to another site	Assembly site	STATS ChipPAC Korea 1 & STATS ChipPAC Korea 3

**4. Description of change**

	<b>Old</b>	<b>New</b>
<b>4.1 Description</b>	STATS ChipPAC Korea 1 assembly site for STR9 products in LFBGA 10x10 package	Transfer assembly site to STATS ChipPAC Korea 3. Same Bill Of Material.
<b>4.2 Anticipated Impact on form, fit, function, quality, reliability or processability?</b>	no change	

**5. Reason / motivation for change**

<b>5.1 Motivation</b>	STATS ChipPAC Korea 1 assembly site closure
<b>5.2 Customer Benefit</b>	SERVICE IMPROVEMENT

**6. Marking of parts / traceability of change**

<b>6.1 Description</b>	Traceability of the change is ensured by ST internal tools. Change of marking : please refer to annex 1 document.
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**7. Timing / schedule**

<b>7.1 Date of qualification results</b>	2015-04-01
<b>7.2 Intended start of delivery</b>	2015-05-01
<b>7.3 Qualification sample available?</b>	Not Applicable

**8. Qualification / Validation**

<b>8.1 Description</b>	9012_QUAL_PLAN_MCD Pkg14 RER1420 STR9 LFBGA10x10 SCK3.pdf		
<b>8.2 Qualification report and qualification results</b>	Available (see attachment)	<b>Issue Date</b>	2014-12-18

**9. Attachments (additional documentations)**

9012PpPrdtLst.pdf  
9012\_QUAL\_PLAN\_MCD Pkg14 RER1420 STR9 LFBGA10x10 SCK3.pdf  
9012\_ANNEX 1.pdf

**10. Affected parts**

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STR912FAZ42H6	

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